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October 2014

CNY171M, CNY172M, CNY173M, CNY174M, CNY17F1M, CNY17F2M, CNY17F3M, CNY17F4M, MOC8106M 6-Pin DIP High BV_{CEO} Phototransistor Optocouplers

Features

- High BV_{CEO}: 70 V Minimum (CNY17XM, CNY17FXM, MOC8106M)
- Closely Matched Current Transfer Ratio (CTR) Minimizes Unit-to-Unit Variation
- Current Transfer Ratio In Select Groups
- Very Low Coupled Capacitance Along With No Chip-to-Pin 6 Base Connection for Minimum Noise Susceptability (CNY17FXM, MOC8106M)
- Safety and Regulatory Approvals:
 - UL1577, 4,170 VAC_{RMS} for 1 Minute
 - DIN-EN/IEC60747-5-5, 850 V Peak Working Insulation Voltage

Applications

- Power Supply Regulators
- Digital Logic Inputs
- Microprocessor Inputs
- Appliance Sensor Systems
- Industrial Controls

Description

The CNY17XM, CNY17FXM, and MOC8106M devices consist of a gallium arsenide infrared emitting diode coupled with an NPN phototransistor in a dual in-line package.

Package Outlines

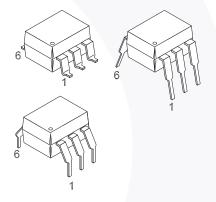
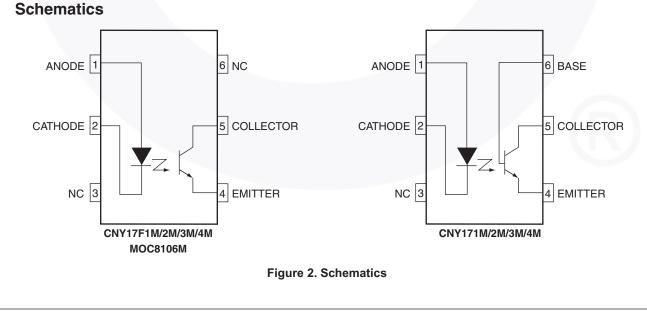


Figure 1. Package Outlines



CNY17XM, CNY17FXM, MOC8106M — 6-Pin DIP High BV_{CEO} Phototransistor Optocouplers

Safety and Insulation Ratings

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

| Parameter | Characteristics | |
|--|------------------------|-----------|
| Installation Classifications per DIN VDE | < 150 V _{RMS} | I–IV |
| 0110/1.89 Table 1, For Rated Mains Voltage | < 300 V _{RMS} | I–IV |
| Climatic Classification | | 55/100/21 |
| Pollution Degree (DIN VDE 0110/1.89) | | 2 |
| Comparative Tracking Index | | 175 |

| Symbol | Parameter | Value | Unit |
|-----------------------|---|-------------------|-------------------|
| V | Input-to-Output Test Voltage, Method A, $V_{IORM} \times 1.6 = V_{PR}$, Type and Sample Test with t _m = 10 s, Partial Discharge < 5 pC | 1360 | V _{peak} |
| V _{PR} | Input-to-Output Test Voltage, Method B, $V_{IORM} \times 1.875 = V_{PR}$, 100% Production Test with $t_m = 1$ s, Partial Discharge < 5 pC | 1594 | V _{peak} |
| VIORM | Maximum Working Insulation Voltage | 850 | V _{peak} |
| V _{IOTM} | Highest Allowable Over-Voltage | 6000 | V _{peak} |
| | External Creepage | ≥ 7 | mm |
| | External Clearance | ≥ 7 | mm |
| | External Clearance (for Option TV, 0.4" Lead Spacing) | ≥ 10 | mm |
| DTI | Distance Through Insulation (Insulation Thickness) | ≥ 0.5 | mm |
| Τ _S | Case Temperature ⁽¹⁾ | 175 | °C |
| I _{S,INPUT} | Input Current ⁽¹⁾ | 350 | mA |
| P _{S,OUTPUT} | Output Power ⁽¹⁾ | 800 | mW |
| R _{IO} | Insulation Resistance at T _S , V_{IO} = 500 V ⁽¹⁾ | > 10 ⁹ | Ω |

Note:

1. Safety limit values - maximum values allowed in the event of a failure.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameters | Value | Units |
|---------------------|---|--------------------|-------|
| TOTAL DE | VICE | | |
| T _{STG} | Storage Temperature | -40 to +125 | °C |
| T _A | Ambient Operating Temperature | -40 to +100 | °C |
| TJ | Junction Temperature | -40 to +125 | °C |
| T _{SOL} | Lead Solder Temperature | 260 for 10 seconds | °C |
| | Total Device Power Dissipation @ 25°C (LED plus detector) | 270 | mW |
| PD | Derate Linearly From 25°C | 2.94 | mW/°C |
| EMITTER | | | |
| I _F | Continuous Forward Current | 60 | mA |
| V _R | Reverse Voltage | 6 | V |
| l _F (pk) | Forward Current – Peak (1 µs pulse, 300 pps) | 1.5 | А |
| P | LED Power Dissipation 25°C Ambient | 120 | mW |
| PD | Derate Linearly From 25°C | 1.41 | mW/°C |
| DETECTO | 2 | | |
| Ι _C | Continuous Collector Current | 50 | mA |
| V _{CEO} | Collector-Emitter Voltage | 70 | V |
| V _{ECO} | Emitter Collector Voltage | 7 | V |
| D | Detector Power Dissipation @ 25°C | 150 | mW |
| PD | Derate Linearly from 25°C | 1.76 | mW/°C |

Electrical Characteristics

 $T_A = 25^{\circ}C$ unless otherwise specified.

Individual Component Characteristics

| Symbol | Parameters | Test Conditions | Device | Min. | Тур. | Max. | Units |
|-------------------|----------------------------|---|----------------------|------|-------|------|-------|
| EMITTER | | | | | | | |
| | | I _F = 10 mA | All Devices | 1.0 | 1.15 | 1.50 | V |
| V_{F} | Input Forward Voltage | I _F = 60 mA | CNY17XM, CNY17FXM | 1.0 | 1.35 | 1.65 | V |
| CJ | Capacitance | V _F = 0 V, f = 1.0 MHz | All Devices | | 18 | | pF |
| I _R | Reverse Leakage Current | V _R = 6 V | All Devices | | 0.001 | 10 | μA |
| DETECTO | DR | | | | | | |
| | Breakdown Voltage | | | | | | |
| BV_{CEO} | Collector-to-Emitter | I _C = 1 mA, I _F = 0 | All Devices | 70 | 100 | | V |
| BV _{CBO} | Collector-to-Base | I _C = 10 μA, I _F = 0 | CNY17XM | 70 | 120 | | V |
| BV _{ECO} | Emitter-to-Collector | I _E = 100 μA, I _F = 0 | All Devices | 7 | 10 | | V |
| | Leakage Current | | | | | | |
| I _{CEO} | Collector-to-Emitter | V _{CE} = 10 V, I _F = 0 | All Devices | | 1 | 50 | nA |
| I _{CBO} | Collector-to-Base | V _{CB} = 10 V, I _F = 0 | CNY17XM | | | 20 | nA |
| | Capacitance | | | | | | |
| C_{CE} | Collector-to-Emitter | V _{CE} = 0, f = 1 MHz | All Devices | | 8 | | pF |
| C _{CB} | Collector-to-Base | V _{CB} = 0, f = 1 MHz | CNY17XM | | 20 | | pF |
| C _{EB} | Emitter-to-Base | V _{EB} = 0, f = 1 MHz | CNY17XM | | 10 | | pF |

Transfer Characteristics

| Symbol | Parameters | Test Conditions | Device | Min. | Тур. | Max. | Units |
|-------------------------------|--|---|-------------------|------|------|------|-------|
| COUPLE |) | | | | | | |
| CTR Current Transfer Ratio | I _F = 10 mA, V _{CE} = 10 V | MOC8106M | 50 | | 150 | % | |
| | $I_F = 10 \text{ mA}, V_{CE} = 5 \text{ V}$ | CNY171M, CNY17F1M | 40 | | 80 | % | |
| | | I _F = 10 mA, V _{CE} = 5 V | CNY172M, CNY17F2M | 63 | | 125 | % |
| | I _F = 10 mA, V _{CE} = 5 V | CNY173M, CNY17F3M | 100 | | 200 | % | |
| | | I _F = 10 mA, V _{CE} = 5 V | CNY174M, CNY17F4M | 160 | | 320 | % |
| V | Collector-Emitter Saturation Voltage | l _C = 0.5 mA, l _F = 5 mA | MOC8106M | | 0.4 | | V |
| | | I _C = 2.5 mA, I _F = 10 mA | CNY17XM/CNY17FXM | | | | v |

Electrical Characteristics (Continued)

 $T_A = 25^{\circ}C$ unless otherwise specified.

AC Characteristics

| Symbol | Parameters | Test Conditions | Device | Min. | Тур. | Max. | Units |
|------------------|---------------|--|-----------------------------------|------|------|------|-------|
| NON-SAT | URATED SWITC | CHING TIME | | | | | |
| t _{on} | Turn-On Time | $I_{\rm C}$ = 2.0 mA, V _{CC} = 10 V, R _L = 100 Ω | All Devices | | 2.0 | 10.0 | μs |
| t _{off} | Turn-Off Time | $I_{\rm C}$ = 2.0 mA, V _{CC} = 10 V, R _L = 100 Ω | All Devices | | 3.0 | 10.0 | μs |
| t _d | Delay Time | I_F = 10 mA, V_{CC} = 5 V, R_L = 75 Ω | CNY17XM/CNY17FXM | | | 5.6 | μs |
| t _r | Rise Time | I_F = 10 mA, V_{CC} = 5 V, R_L = 75 Ω | CNY17XM/CNY17FXM | | | 4.0 | μs |
| ts | Storage Time | I_F = 10 mA, V_{CC} = 5 V, R_L = 75 Ω | CNY17XM/CNY17FXM | | | 4.1 | μs |
| t _f | Fall Time | I_F = 10 mA, V_{CC} = 5 V, R_L = 75 Ω | CNY17XM/CNY17FXM | | | 3.5 | μs |
| SATURA | TED SWITCHING | TIMES | | | | | |
| | | I_F = 20 mA, V_{CC} = 5 V, R_L = 1 k Ω | CNY171M/F1M | | | 5.5 | μs |
| t _d | Delay Time | I_F = 10 mA, V_{CC} = 5 V, R_L = 1 k Ω | CNY172M/3M/4M CNY17F2M/F3M/F4M | | | 8.0 | μs |
| | | I_F = 20 mA, V _{CC} = 5 V, R _L = 1 kΩ | CNY171M/F1M | | | 4.0 | μs |
| t _r | Rise Time | I_F = 10 mA, V_{CC} = 5 V, R_L = 1 k Ω | CNY172M/3M/4M CNY17F2M/F3M/F4M | | | 6.0 | μs |
| | / | I_F = 20 mA, V_{CC} = 5 V, R_L = 1 k Ω | CNY171M/F1M | | | 34.0 | μs |
| t _s | Storage Time | I_F = 10 mA, V_{CC} = 5 V, R_L = 1 k Ω | CNY172M/3M/4M CNY17F2M/F3M/F4M | | | 39.0 | μs |
| | | I_F = 20 mA, V_{CC} = 5 V, R_L = 1 k Ω | CNY171M/F1M | | | 20.0 | μs |
| t _f | Fall Time | I_F = 10 mA, V_{CC} = 5 V, R_L = 1 k Ω | CNY172M/3M/4M CNY17F2M/F3M/F4M | | | 24.0 | μs |

Isolation Characteristics

| Symbol | Characteristic | Test Conditions | Min. | Тур. | Max. | Units |
|------------------|--------------------------------|--|------------------|------|------|--------------------|
| V _{ISO} | Input-Output Isolation Voltage | t = 1 Minute | 4170 | | | VAC _{RMS} |
| C _{ISO} | Isolation Capacitance | V _{I-O} = 0 V, f = 1 MHz | | 0.2 | | pF |
| R _{ISO} | Isolation Resistance | V _{I-O} = ±500 VDC, T _A = 25°C | 10 ¹¹ | | | Ω |



100

1000

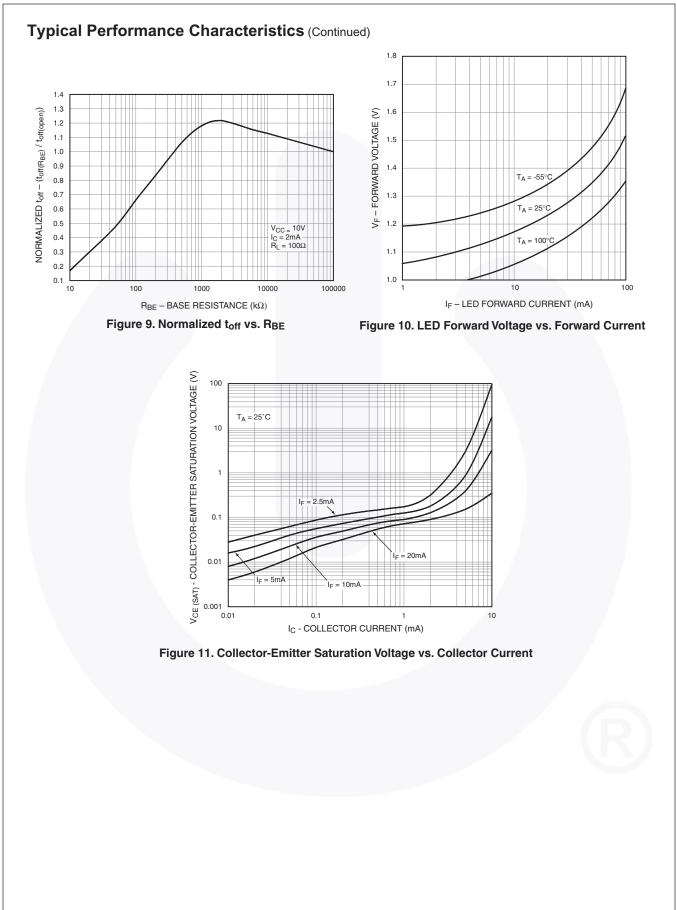
1.6 $V_{CE} = 5.0 V$ $T_A = 25^{\circ}C$ Normalized to I_F = 10 mA 1.2 1.4 $l_{\rm E} = 5 \, \rm{mA}$ 1.2 1.0 $I_F = 10 \text{ mA}$ NORMALIZED CTR 1.0 **NORMALIZED CTR** 0.8 0.8 $I_{\rm F} = 20 \, {\rm mA}$ 0.6 0.6 0.4 0.4 Normalized to: I_F = 10 mA 0.2 T_A = 25°C 0.2 0.0 -60 -40 -20 0 20 40 60 80 0 2 18 20 4 6 8 10 12 14 16 IF - FORWARD CURRENT (mA) T_A – AMBIENT TEMPERATURE (°C) Figure 3. Normalized CTR vs. Forward Current Figure 4. Normalized CTR vs. Ambient Temperature 1.0 NORMALIZED CTR (CTR_{RBE} / CTR_{RBE}(OPEN)) 1.0 NORMALIZED CTR (CTR_{RBE} / CTR_{RBE}(OPEN)) 0.9 0.9 $I_F = 20 \text{ mA}$ 0.8 0.8 $I_{\rm F} = 10 \, {\rm m/}$ = 5 mA $V_{CF} = 0.3 V$ 0.7 0.7 20 n 0.6 0.6 0.5 0.5 = 10 mA IF. 0.4 0.4 0.3 0.3 $I_F = 5 \text{ mA}$ 0.2 0.2 V_{CE} = 5.0 V 0.1 0.1 0.0 0.0 10 100 1000 10 100 R_{BE} – BASE RESISTANCE (k Ω) $R_{BE} - BASE RESISTANCE (k\Omega)$ Figure 5. CTR vs. RBE (Unsaturated) Figure 6. CTR vs. RBE (Saturated) 1000 $I_F = 10 \text{ mA}$ $V_{CC} = 10 \text{ V}$ $T_A = 25^{\circ}\text{C}$ 5.0 100 $V_{CC} = 10 V$ $I_{C} = 2 mA$ $R_{L} = 100 \Omega$ $\mathsf{NORMALIZED} \ t_{\mathsf{on}} - (t_{\mathsf{on}(\mathsf{R}_{\mathsf{BE}})} \ / \ t_{\mathsf{on}(\mathsf{open})})$ 4.5 SWITCHING SPEED (µs) 4.0 10 3.5 3.0 Т 2.5 T_r 2.0 1.5 1.0 0.1 0.5 **L** 10 0.1 10 100 100 1000 10000 R – LOAD RESISTOR (kΩ) R_{BE} – BASE RESISTANCE (k Ω) Figure 8. Normalized ton vs. RBE Figure 7. Switching Speed vs. Load Resistor

1.4

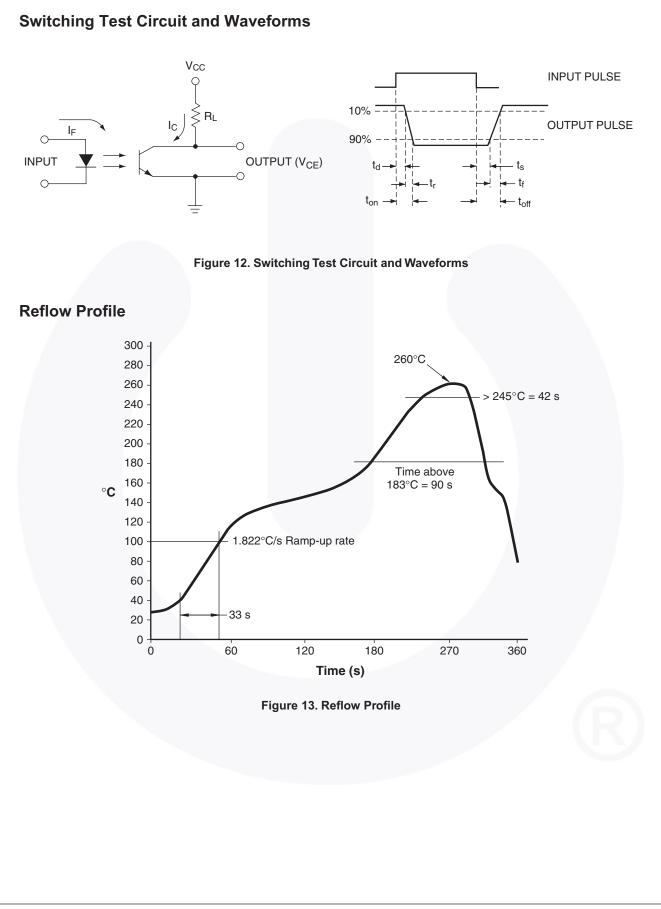
©2006 Fairchild Semiconductor Corporation CNY17XM, CNY17FXM, MOC8106M Rev. 1.1.2

Typical Performance Characteristics

100000



7



Ordering Information

| Part Number | Package | Packing Method |
|-------------|--|----------------------------|
| CNY171M | DIP 6-Pin | Tube (50 Units) |
| CNY171SM | SMT 6-Pin (Lead Bend) | Tube (50 Units) |
| CNY171SR2M | SMT 6-Pin (Lead Bend) | Tape and Reel (1000 Units) |
| CNY171TM | DIP 6-Pin, 0.4" Lead Spacing | Tube (50 Units) |
| CNY171VM | DIP 6-Pin, DIN EN/IEC60747-5-5 Option | Tube (50 Units) |
| CNY171SVM | SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option | Tube (50 Units) |
| CNY171SR2VM | SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option | Tape and Reel (1000 Units) |
| CNY171TVM | DIP 6-Pin, 0.4" Lead Spacing, DIN EN/IEC60747-5-5 Option | Tube (50 Units) |

Note:

2. The product orderable part number system listed in this table also applies to the CNY17FXM product family and the MOC8106M device.

Marking Information

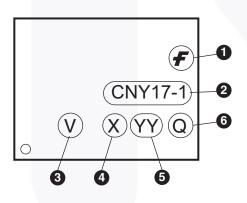


Figure 14. Top Mark

Table 1. Top Mark Definitions

| 1 | Fairchild Logo |
|---|---|
| 2 | Device Number |
| 3 | DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option) |
| 4 | One-Digit Year Code, e.g., "4" |
| 5 | Digit Work Week, Ranging from "01" to "53" |
| 6 | Assembly Package Code |











NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
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- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
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